



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-07-20
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L6225DTR	A6Z7*UR29AD6	A	MUAR B/E	2015-07-20
	Amount	UoM	Unit type	ST ECOPACK Grade
	534.52	mg	Each	ECOPACK1

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	250	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	NiPdAu	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	3.9, 4.9, 1.25	20	GULL WING	
Comment	Package: SO 20 .30 TO JEDEC MS-013			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2014				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	A6Z7*UR29AD6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	9.464	mg	supplier	die	Silicon (Si)	7440-21-3		9.109	mg	962485	17040
				supplier	metallization	Aluminium (Al)	7429-90-5		0.069	mg	7292	129
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	845	15
				supplier	Passivation	Silicon Nitride	12033-89-5		0.020	mg	2113	37
				supplier	Passivation	Silicon Oxide	7631-86-9		0.119	mg	12575	223
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.005	mg	528	9
				supplier	back side metallization	Gold (Au)	7440-57-5		0.014	mg	1479	26
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.046	mg	4861	86
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.074	mg	7820	138
				Leadframe	Copper & Its alloys	172.179	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						0.079	mg	459	148
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.145	mg	842	271
supplier	metallization	Nickel (Ni)	7440-02-0						0.032	mg	186	60
supplier	metallization	Palladium (Pd)	7440-05-3						0.002	mg	12	4
supplier	metallization	Gold (Au)	7440-57-5						0.001	mg	6	2
Die attach	Other Organic Materials	2.034	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		1.566	mg	769912	2930
				supplier	glue or tape	Epoxy Cresol Novolak	29690-82-2		0.460	mg	226155	861
				supplier	glue or tape	1-isopropyl-2,2-dimethyltrimethylene diisobut	6846-50-0		0.008	mg	3933	15
Bonding wires	Other inorganic materials	0.395	mg	supplier	wire	Gold (Au)	7440-57-5		0.395	mg	1000000	739
Encapsulation	Other Organic Materials	350.448	mg	supplier	mold compound	Silica, vitreous	60676-86-0		282.462	mg	806003	528440
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		24.531	mg	69999	45894
				supplier	mold compound	Phenol resin	9003-35-4		14.018	mg	40000	26225
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		21.027	mg	60000	39338
				supplier	mold compound	Antimony Trioxide	1309-64-4		4.205	mg	11999	7867
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		2.453	mg	7000	4589
				supplier	mold compound	Carbon black	1333-86-4		1.752	mg	4999	3278